

CBR02C809B3GAC

CBR-SMD RF COG, Ceramic, 8 pF, +/-0.1 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



Click [here](#) for the 3D model.

| Dimensions | |
|------------|------------------|
| Chip Size | 0201 |
| L | 0.6mm +/-0.03mm |
| W | 0.3mm +/-0.03mm |
| T | 0.3mm +/-0.03mm |
| B | 0.15mm +/-0.05mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 15000 |

| General Information | |
|---------------------|--|
| Series | CBR-SMD RF COG |
| Style | SMD Chip |
| Description | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features | Ultra High Q, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 0.3 mg |
| Notes | Solder Reflow Only. |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|---------------------------------|---------------------|
| Capacitance | 8 pF |
| Capacitance Tolerance | +/-0.1 pF |
| Voltage DC | 25 VDC |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Dissipation Factor | 0.179% |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 560 |

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